

NCE N-Channel Super Junction Power MOSFET (With Fast Body Diode)

General Description

The series of devices use advanced super junction technology and design to provide excellent RDS(ON) with low gate charge. This super junction MOSFET fits the industry's AC-DC SMPS requirements for PFC, AC/DC power conversion, and industrial power applications.

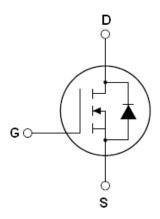
Features

- New technology for high voltage device
- ●Low on-resistance and low conduction losses
- Intrinsic fast-recovery body diode
- Extreme low reverse recovery charge
- ●100% Avalanche Tested
- ●ROHS compliant

Application

- Power factor correction (PFC)
- Switched mode power supplies(SMPS)
- Uninterruptible Power Supply (UPS)
- Strongly recommended for bridge topologies

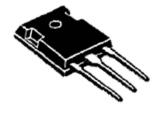
V_{DS}	650	V
R _{DS(ON)}	410	mΩ
I_D	11	A



Schematic diagram

Package Marking And Ordering Information

	<u> </u>		
Device	Device Package	Marking	
NCE11NF65T	TO-247	NCE11NF65T	



TO-247

Table 1. Absolute Maximum Ratings (T_C=25℃)

Parameter	Symbol	NCE11NF65T	Unit
Drain-Source Voltage (V _{GS=0} V)	V _{DS}	650	V
Gate-Source Voltage (VDS=0V)	V _G s	±30	V
Continuous Drain Current at Tc=25°C	I _{D (DC)}	11	Α
Continuous Drain Current at Tc=100°C	I _{D (DC)}	7	А
Pulsed drain current (Note 1)	I _{DM (pluse)}	33	А
Drain Source voltage slope, VDS = 480 V, ID = 11 A, Tj = 125 °C	dv/dt	50	V/ns
Maximum Power Dissipation(Tc=25℃)	P _D	125	W
Derate above 25°C		1	w/°C
Single pulse avalanche energy (Note2)	Eas	340	mJ
Avalanche current ^(Note 1)	I _{AR}	11	Α



Parameter	Symbol	NCE11NF65T	Unit
Repetitive Avalanche energy , t_{AR} limited by T_{jmax} (Note 1)	E _{AR}	0.6	mJ
Operating Junction and Storage Temperature Range	T_{J}, T_{STG}	-55+150	°C

^{*} limited by maximum junction temperature

Table 2. Thermal Characteristic

Parameter	Symbol	NCE11NF65T	Unit
Thermal Resistance, Junction-to-Case (Maximum)	R_{thJC}	1	°C /W
Thermal Resistance, Junction-to-Ambient (Maximum)	R _{thJA}	62	°C /W

Table 3. Electrical Characteristics (TA=25^oC unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
On/off states						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	650			V
Zero Gate Voltage Drain Current(Tc=25℃)	I _{DSS}	V _{DS} =650V,V _{GS} =0V			1	μΑ
Zero Gate Voltage Drain Current(Tc=125℃)	I _{DSS}	V _{DS} =650V,V _{GS} =0V			100	μA
Gate-Body Leakage Current	I _{GSS}	V_{GS} =±30 V , V_{DS} =0 V			±100	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}$, $I_{D}=250\mu A$	3		5	٧
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =7A		370	410	mΩ
Dynamic Characteristics						
Forward Transconductance	g FS	$V_{DS} = 20V, I_{D} = 7A$		8.5		S
Input Capacitance	C _{lss}	\/ -50\/\/ -0\/		1270		pF
Output Capacitance	Coss	V_{DS} =50V, V_{GS} =0V, F=1.0MHz		106		pF
Reverse Transfer Capacitance	C _{rss}	F=1.0IVIFIZ		5.5		pF
Total Gate Charge	Q_g	\/ -490\/ -414		28	60	nC
Gate-Source Charge	Q_{gs}	V _{DS} =480V,I _D =11A,		6.5		nC
Gate-Drain Charge	Q_{gd}	V _{GS} =10V		9.5		nC
Intrinsic gate resistance	R_G	f = 1 MHz open drain		1.5		Ω
Switching times						
Turn-on Delay Time	t _{d(on)}			10		nS
Turn-on Rise Time	t _r	V _{DD} =380V,I _D =11A,		5		nS
Turn-Off Delay Time	$t_{d(off)}$	R_G =6.8 Ω , V_{GS} =10 V		44	70	nS
Turn-Off Fall Time	t _f			5	9	nS
Source- Drain Diode Characteristics						
Source-drain current(Body Diode)	I _{SD}	T _C =25°C			11	Α
Pulsed Source-drain current(Body Diode)	I _{SDM}	10-25 C			33	Α
Forward on voltage	V _{SD}	Tj=25°C,I _{SD} =11A,V _{GS} =0V		1	1.3	V
Reverse Recovery Time	t _{rr}			140		nS
Reverse Recovery Charge	Qrr	Tj=25°C,I _F =11A,di/dt=100A/μs		0.85		uC
Peak Reverse Recovery Current	I _{rrm}			12		Α

Notes: 1.Repetitive Rating: Pulse width limited by maximum junction temperature

^{2.} Tj=25 $^{\circ}\text{C}$,VDD=50V,VG=10V, RG=25 Ω



TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (curves)

Figure 1. Safe operating area

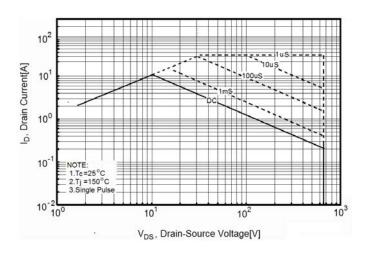


Figure 2. Source-Drain Diode Forward Voltage

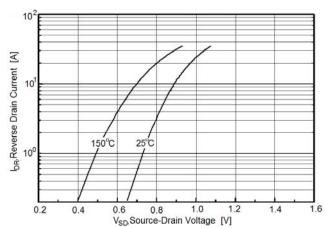


Figure 3. Output characteristics

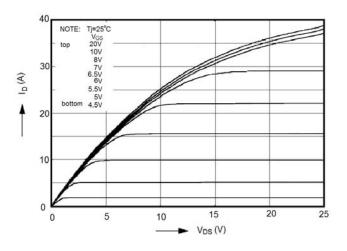


Figure 4. Transfer characteristics

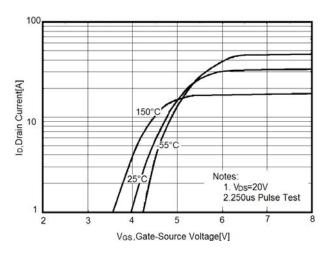
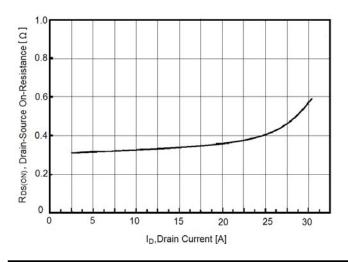


Figure 5. Static drain-source on resistance



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Figure 6. R_{DS(ON)} vs Junction Temperature

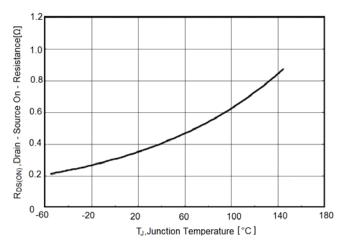




Figure 7. BV_{DSS} vs Junction Temperature

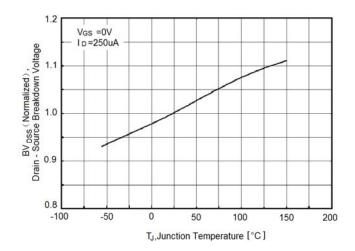


Figure 9. Gate charge waveforms

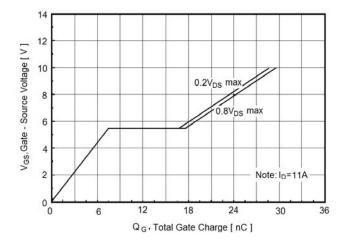


Figure 11. Transient Thermal Impedance

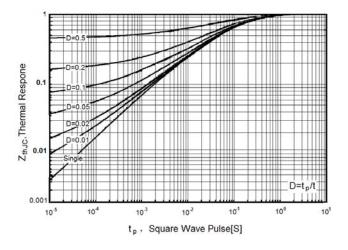


Figure 8. Maximum I_D vs Junction Temperature

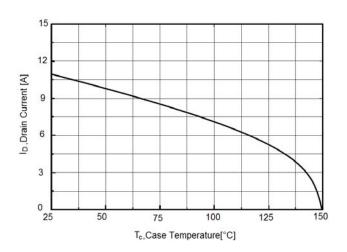
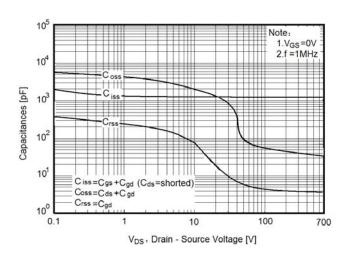


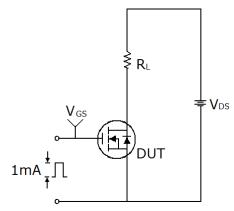
Figure 10. Capacitance

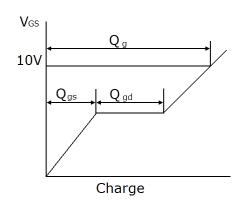




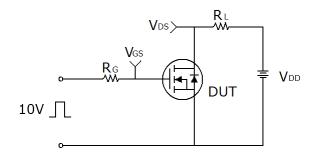
Test circuit

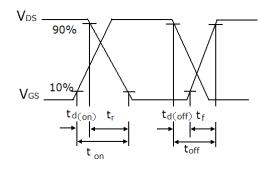
1) Gate charge test circuit & Waveform



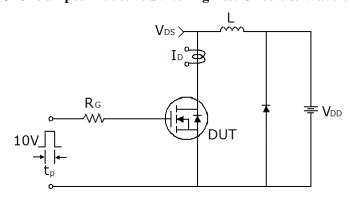


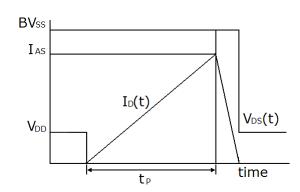
2) Switch Time Test Circuit:





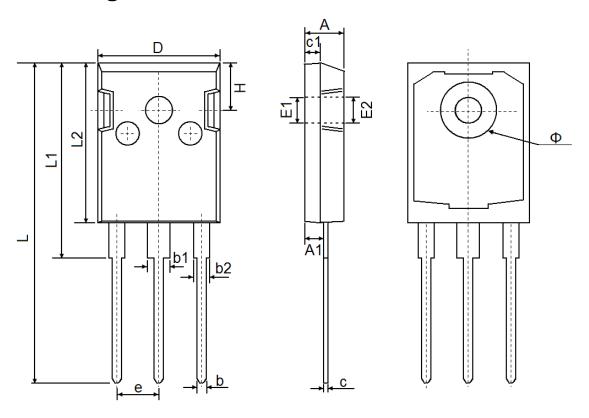
3) Unclamped Inductive Switching Test Circuit & Waveforms







TO-247 Package Information



Combal	Dimensions	In Millimeters	Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
Α	4.850	5.150	0.191	0.200	
A1	2.200	2.600	0.087	0.102	
b	1.000	1.400	0.039	0.055	
b1	2.800	3.200	0.110	0.126	
b2	1.800	2.200	0.071	0.087	
С	0.500	0.700	0.020	0.028	
c1	1.900	2.100	0.075	0.083	
D	15.450	15.750	0.608	0.620	
E1	3.500 REF		0.138 REF		
E2	3.60	3.600 REF		0.142 REF	
L	40.900	41.300	1.610	1.626	
L1	24.800	25.100	0.976	0.988	
L2	20.300	20.600	0.799	0.811	
Ф	7.100	7.300	0.280	0.287	
е	5.45	0 TYP	0.215 TYP		
Н	5.98	5.980 REF 0.235 REF			



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